

Safe Harbor



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Two sides of one coin...

- Much the same
- Cut from the same cloth
- Double-edged sword
- Two peas in a pod
- Adjacent
- Apples and oranges
- Two of a kind
- In the same league
- On equal footing
- Interchangeable
- Parallel
- Same same, but different
- Indistinguishable



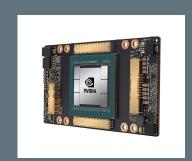
...different ways of looking at or dealing with the same situation...



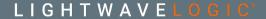


Microelectronics...

- Microelectronics is the manufacture (or microfabrication) of very small electronic designs and components.
- These devices are typically made from semiconductor materials in silicon foundries
- Many components are available in a microelectronic equivalent.
 These include transistors, capacitors, inductors, resistors, diodes and, insulators and conductors etc.
- Unique wiring techniques such as wire bonding, flip chip bumping are also often used because of the unusually small size of the components, leads and pads.

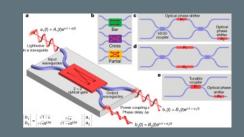


...micro-digital integrated circuits for electronics...



Photonics...

- A photonic integrated circuit (*PIC*) is a microchip containing two or more photonic components which form a functioning circuit.
- PIC technology detects, generates, transports, and processes light. *PICs utilize photons* (or particles of light)
- A PIC provides functions for information signals imposed on optical wavelengths typically in the visible spectrum or near infrared (850–1650 nm).

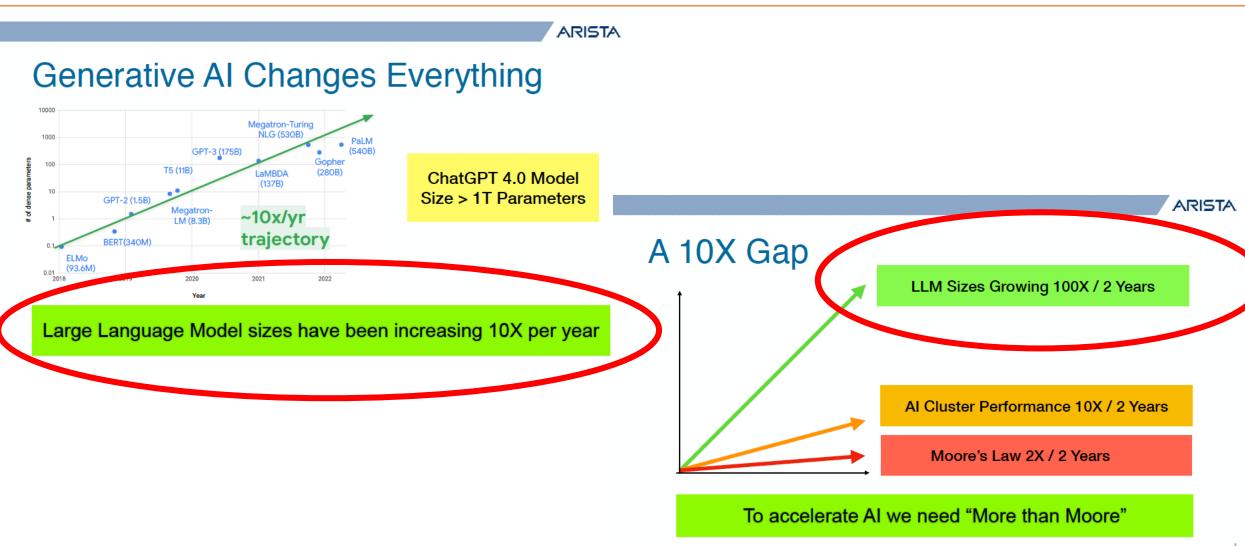


...Photonicsintegrated circuit(PIC) 2 or morecomponents...



New frontiers in electronics and photonics

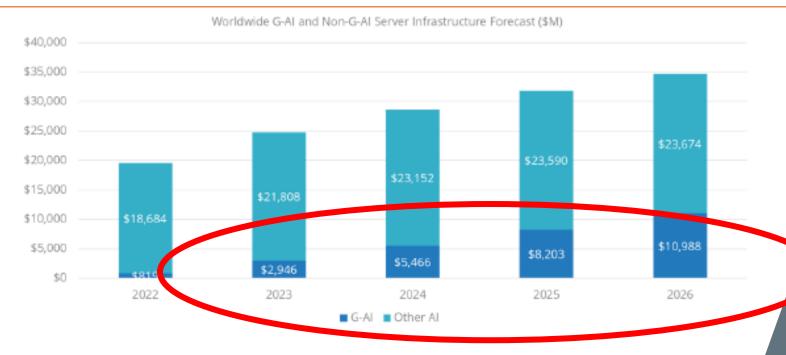




G-AI is driving new frontiers in both electronics and photonics

General-AI market growing quickly





Source: IDC

Estimated CAGR for "Al-Transceivers" alone is 44%

The driver for upgrading transceiver optics in the datacenter and optical network...

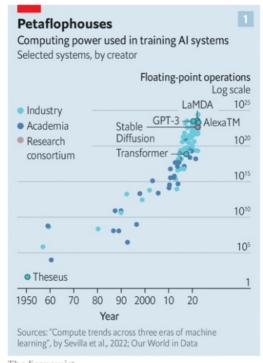
~20% of G-AI data center capex is expected to be 800G transceivers (\$3B in 2026)

Source: Lightwave Logic (LWLG), IDC

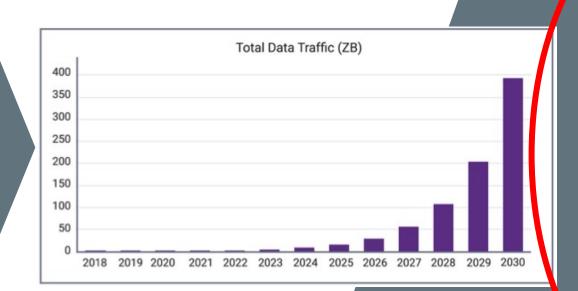
The importance of photonics in communications



LIGHTWAVELOGIC



The Economist



The growth driver of "communication" is datacom...

...The growth driver of datacom is largely Generative Al

The twin enablers of G-AI are photonics and GPUs

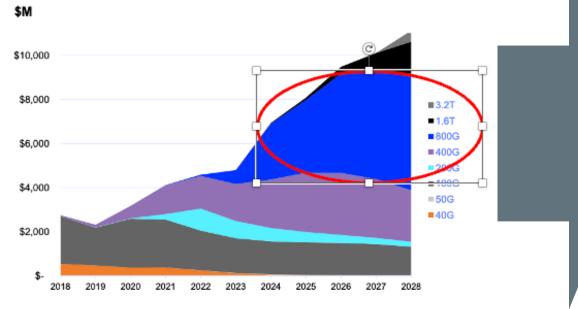
Datacom → Generative AI → Electronics (GPU) and photonics

11 Source: Lightwave Logic (LWLG), Economist, Cisco

The importance of photonics in communications







Source: LightCounting, Internal Estimates

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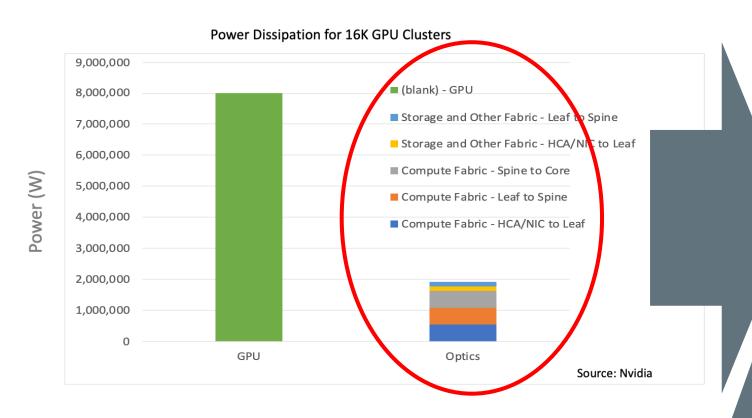
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800Gbps and 1600 Gbps transceiver modules

Need to upgrade in speed, and lower power consumption

Optics is No Longer A "Minor" Contributor to Datacenter G-Al Power Issues





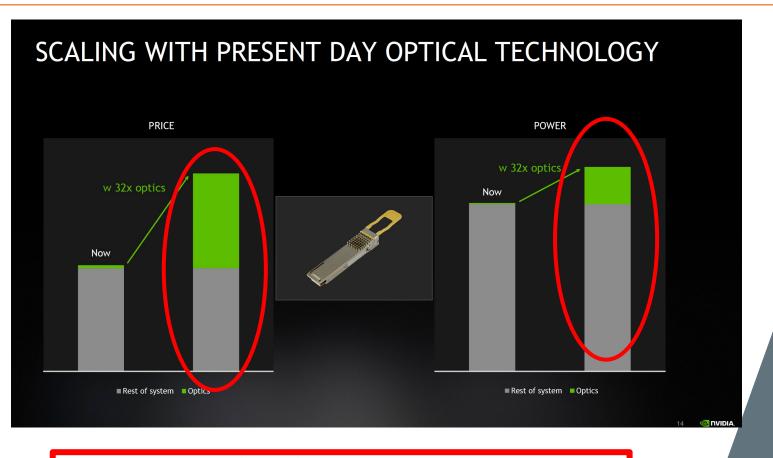
Large language models requires large GPU clusters (ChatGPT 4 training requires ~25,000 GPUs)

For 16,000 GPU clusters, optics consume ~2MW (equivalent to 4000 GPUs) – source: Nvidia, CIOE, Song, 2023)

Power dissipation for AI cluster optics showing optical network power dissipation share increasing...

General-AI market growing quickly





With faster (32x) optics - it becomes a huge effect on price and power

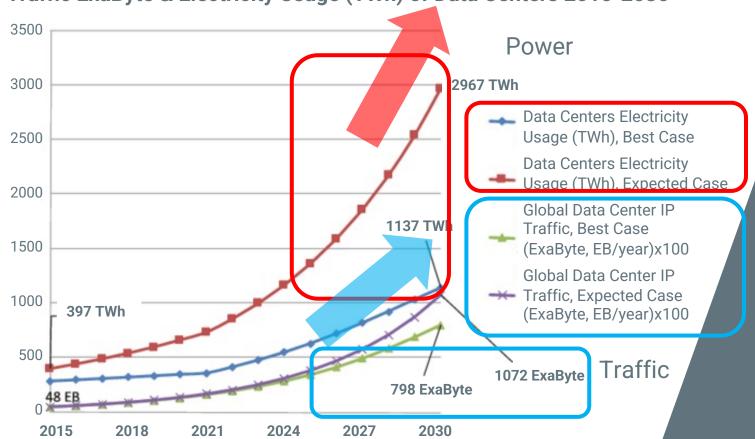
Datacenter photonics needs to improve quickly....





Existing solutions require excessive amounts of power to scale

Traffic ExaByte & Electricity Usage (TWh) of Data Centers 2015-2030



Data center power use is growing exponentially with increased traffic levels - the Achilles Heel and a major challenge for data centers and service providers



Role of photonics as part of the solution



Key Requirements for Optics at AI Scale

Reliability

Need two orders of improvement to single-digit FITS per Terabit

Power Efficiency

Saving 10 pJ/Bit at 2.5 Exabit/sec equals 25 Megawatts

Cost per Bit

Need to drive from double-digit to single cents/Gigabit.

Progress is being made on all of these fronts. but progress needs to be accelerated

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How to Reduce Optics Power

1. Use Linear Drive Interface

Eliminates DSP/CDR power and cost

2. Use lower power modulators

Lower drive voltage, lower insertion losses

3. Use higher efficiency lasers with better coupling

Laser efficiency makes a major difference in overall power

In combination these reduce optics power from 15 pJ/Bit to 5 pJ/Bit, a reduction of 10 pJ/Bit

Arista wish...

Arista wish...

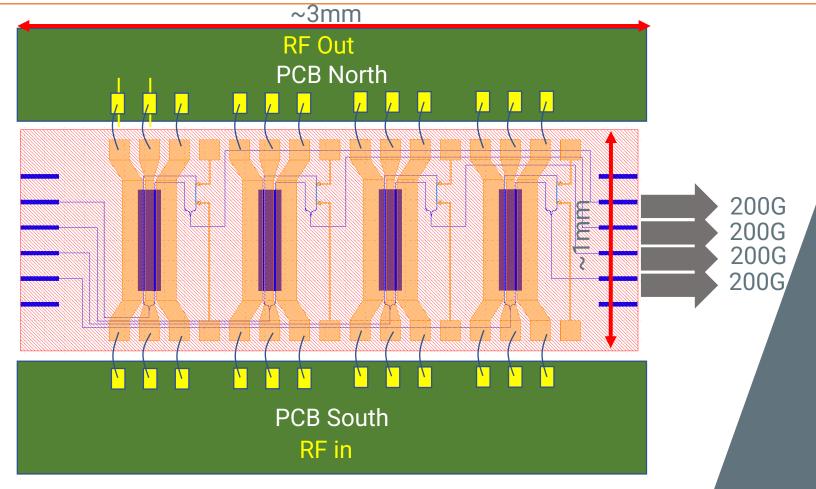
Both electronics and photonics needs to improve... ...especially

modulators

17 Source: Lightwave Logic (LWLG), Arista

Modulators will be part of the solution





In development → 4 channel polymer PIC chip as part of our P²IC platform

Potential for 300G and even 400G per lane*

- Optical 4 channel Polymer PIC layout with Mach Zehnder Interferometers (MZI) arrays
- Fiber array to be connected on both East and West side using Edge couplers
- Electrical CPW transmission length ~1mm

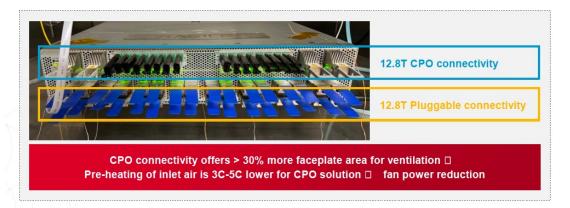
^{*}Using EO S21 3dB bandwidths in excess of 150GHz, with the potential for >250GHz

Packaging will be part of the solution

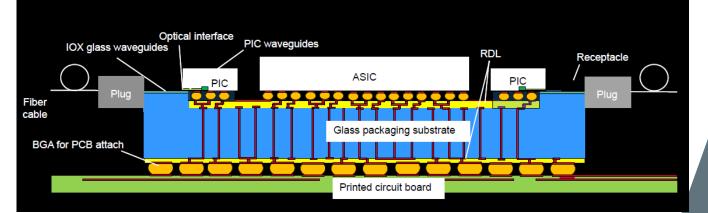


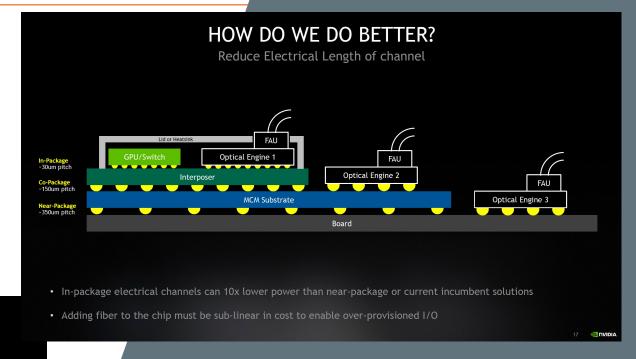
LIGHTWAVELOGIC

25.6T System Solutions Show Roadmap to 51.2T 1RU Solutions



Packaging substrate made of glass that enables pick-and place assembly for high-density optical and electrical connections





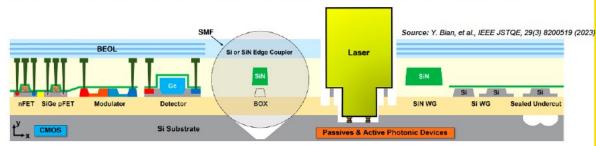
Packaging is becoming more complex...trend to chip-scale solutions

Foundries will be part of the solution

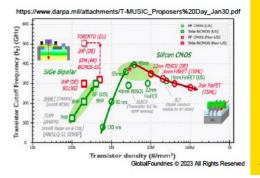


LIGHTWAVELOGIC

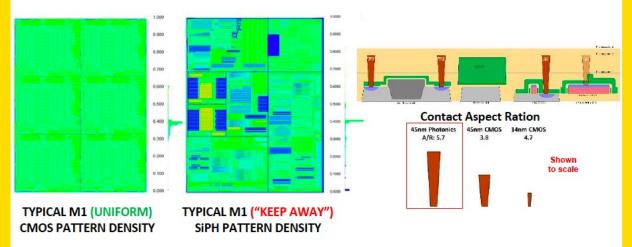
GF Fotonix™: Monolithic Silicon Photonics



- Monolithic integration of Photonic Devices with a 45nm class RFCMOS
- 300mm process leveraging immersion lithography
- Advanced immersion lithography SOI WGs and photonic OPC
- Features
 - Comprehensive photonic passive device library
 - High performance photonic active devices
 - · High efficiency sealed undercut (airgap) thermal heaters
 - · Micro-ring modulators and dWDM ring filters
 - Freeform design enabled: accepts custom curve-linear GDS
- Packaging: V-groove fiber attach, laser cavity, Cu pillar & TSV
- Test: Wafer level state-of-art optical / electrical test capability



GF Fotonix™: Process Window

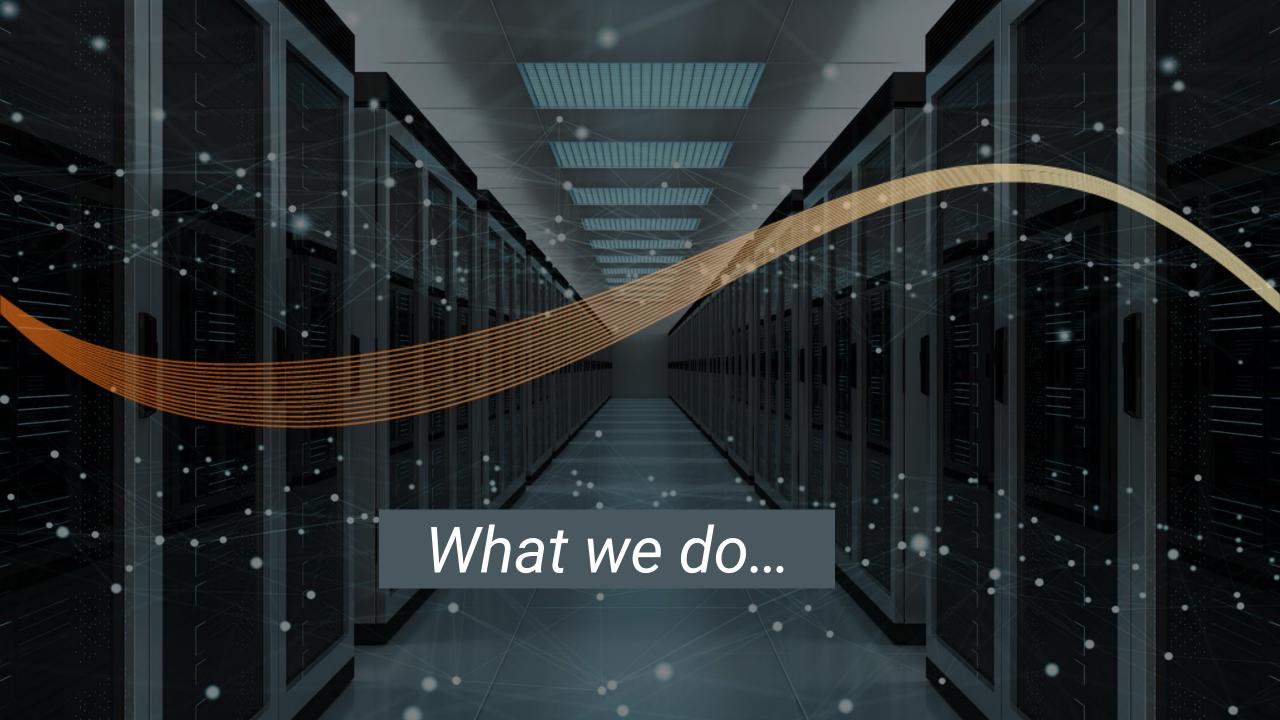


Process windows are reduced due to keep away zones & high aspect ratios

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Creating PDKs for silicon photonics (that include hybrid technologies)

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Perkinamine® Electro-Optic polymers



Our polymers are world-class and proven by third parties

Electro-optic polymers can be used to fabricate optical modulators which enable:



- High material-level thermal and photostability
- Long-term storage and operational durability
- >3x faster modulation than existing products
- ~10x lower power than existing products

EO polymers → Fast, stable, reliable, low power consumption, and very small in size

3rd Party Use of Perkinamine[®]

- EO polymer used in different device designs
- Silicon slot, plasmonic slot, plasmonic ring resonator
- All produced world class results*
- Presentations at industry conferences globally

Sources*: Nature Photonics: Resonant plasmonic micro-racetrack modulators with high bandwidth and high temperature tolerance (ETH Zurich, Polariton and LWLG EO polymer material)

Sources*: KIT, SilOriX, EU Horizon 2020, ETH Zurich, Polariton, CAU University Kiel (post deadline paper published at ECOC2022 using LWLG EO polymers)

Polymer modulator opportunities

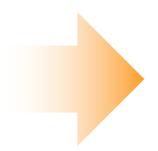


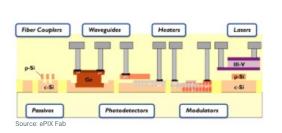
Electro-optic polymer modulators for transceivers suppliers



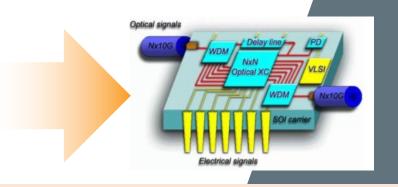


Electro-optic polymer modulators for Silicon Photonic platforms





Electro-optic polymer modulators for "Other" platforms including optical/quantum computing, HPC, and RF applications



EO polymers enable higher performance data communications

Electro-optic polymer engines for fiber optic communications

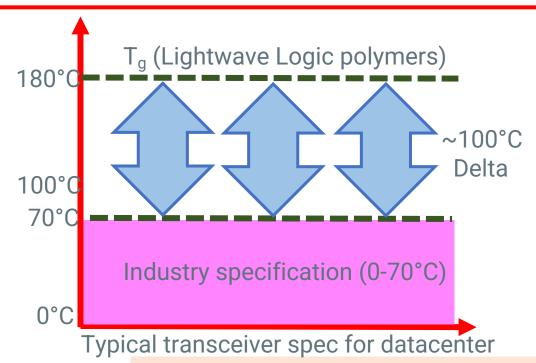


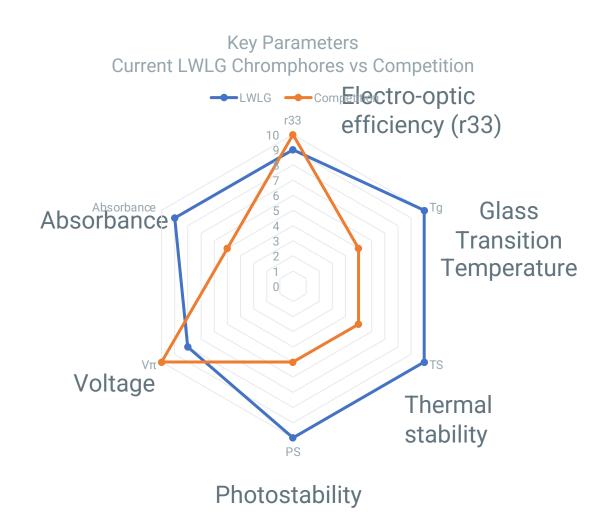
Optimized for reliability & stability



World class chromophore design

- Very high glass transition temperature (T_a)
- ~100°C delta between industry spec and T_q
- Eliminates need for cross-linking
- Protects material from de-poling (occurs when T_g is close to industry specification high limit)

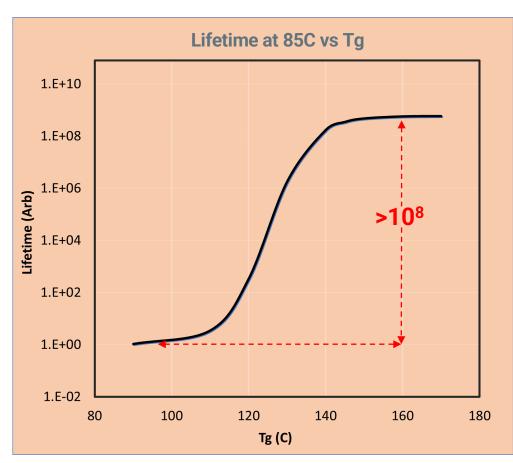




Electro-optic material designed for reliability, stability, and overall operational performance

How important is glass transition temperature (T_g) ?





The thermal lifetime of an EO-polymer material at 85C will increase with increasing Tg

The lifetime at 85° C for a polymer with T_g = 160° C is > 10^{8} times greater than the lifetime for a polymer with T_g = 90° C

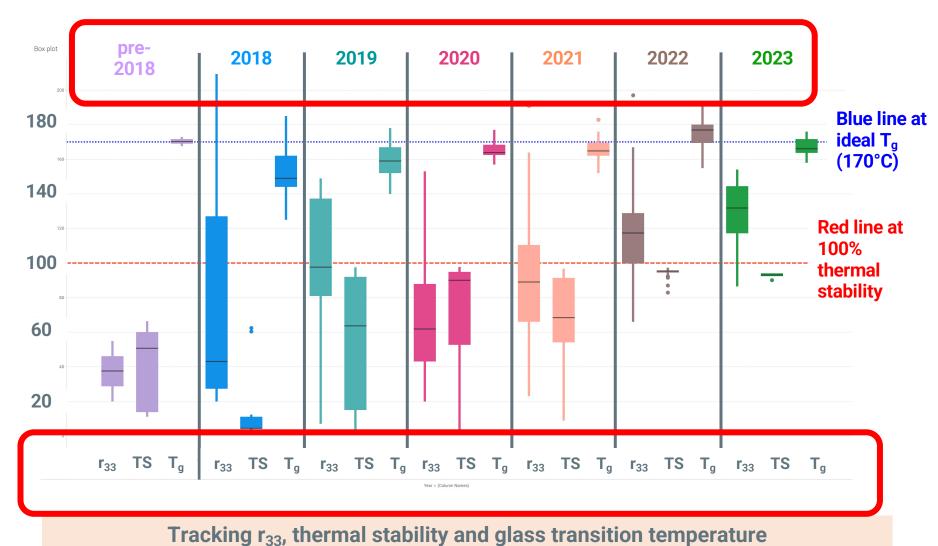
Increasing Tg →
means much
higher lifetime in
electro-optic
materials

Using the widely quoted Lindsay's time constant formula which is found in **Polymer 48 (2007) 6605-6616** $\ln(\tau/\tau_{\rm P}) = E_{\rm R} \left(1 + \tanh\left[\left(T_{\rm c} - T\right)/D\right]\right)/2RT + E_{\rm p}/RT$



LIGHTWAVELOGIC®

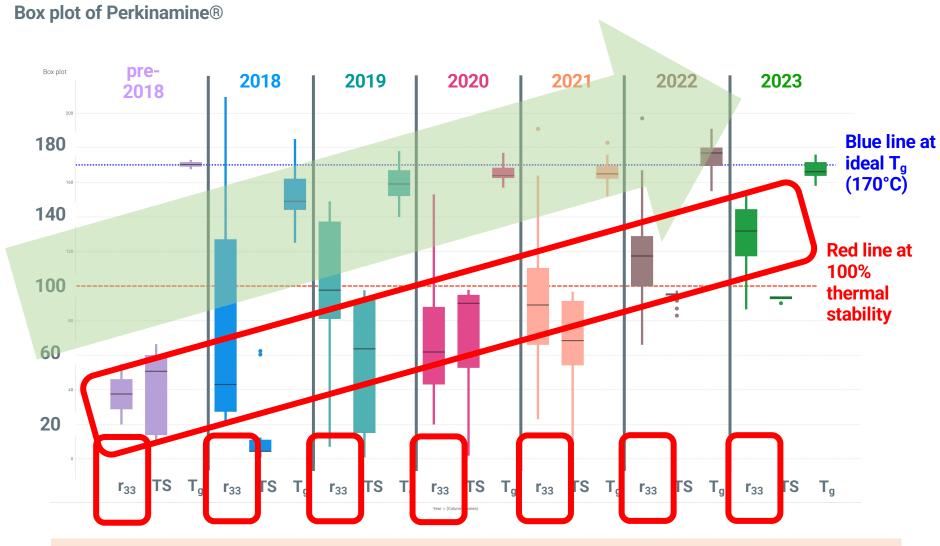
Box plot of Perkinamine®



A box plot or boxplot is a method for graphically demonstrating the locality, spread and skewness groups of numerical data through their quartiles Source: Lightwave Logic (LWLG), *best estimates;

Tracking r₃₃ improvements



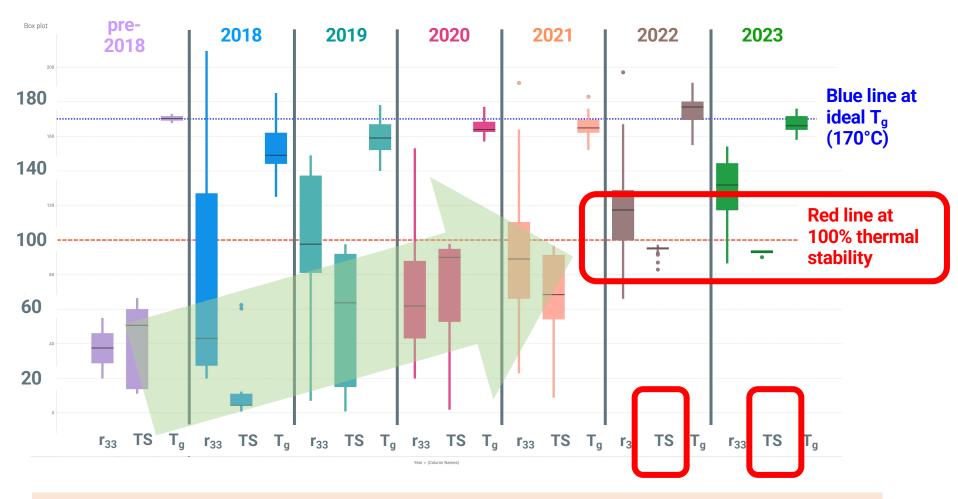


r₃₃ improved 5X over past 6 years; and now very stable in testing

Tracking TS (Thermal Stability) improvements



Box plot of Perkinamine®

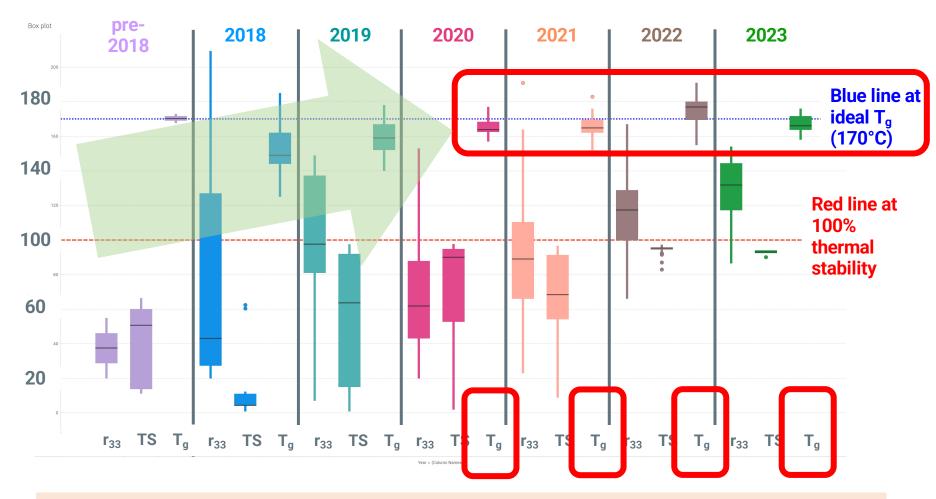


Super performance of material thermal stability in last 2 years (approaching 100%)

Tracking glass transition temperature (T_g)



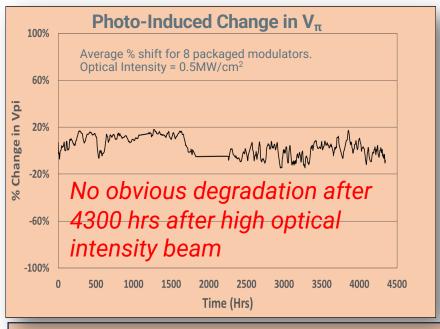
Box plot of Perkinamine®

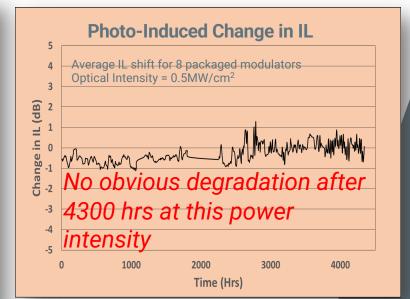


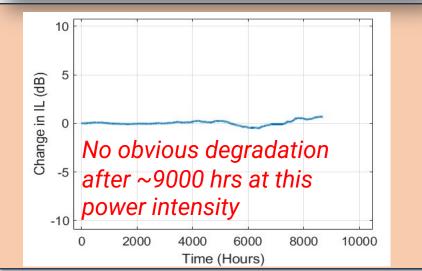
Tight control of materials with extremely high T_q at 170C

Photostability vs Voltage and Insertion Loss





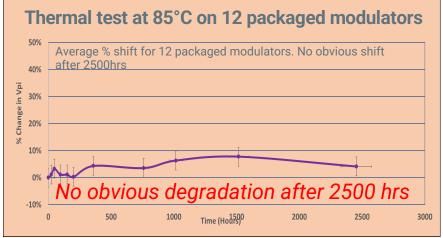


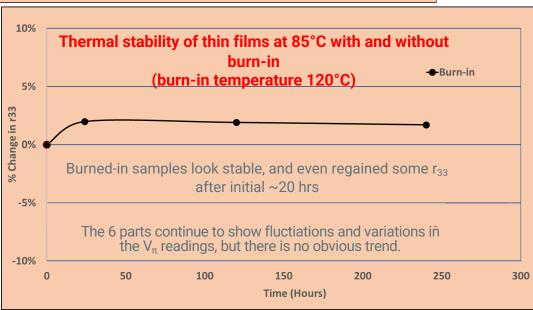


Long and shortterm photostability does not seem to be an issue with LWLG electrooptic chromophores

Device Thermal Stability (TS) against change in voltage







Thermal stability does not seem to be an issue with LWLG packaged modulators or burn-in against change in r₃₃

Polymers (organics) on system roadmap



ARISTA

EOM Technology Comparison

Technology	Integration Capability	Bandwidth	Vpi (1)	Insertion Loss (2)	Reliability	HVM (3)
Silicon Photonics	Excellent	Good	High	High	Proven	Now
III-V	Low	Higher	Lower	Low	Proven	Now
TFLN	Low	Very High	Lower	Low	Proven	2024 (E)
вто	New Process	Very High	Low	Low	Proven	2025 (E)
Organic	New Process	Very High	Lowest) Low C	To be Proven	2026 (E)

Arista wish...

- (1) Tx Drive power is CV^2 -f-dominated
- (2) Lower insertion loss reduces laser power
- (3) HVM = High volume manufacturing

Lower Vpi Drive Voltage results in significant power reduction

Our focus is on:

1) lifetime & reliability2) TTM (time to market)

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Implementing a new technology platform...



Licensing model provides inherent scalability

Technology

Chromophore & Polymer Matrix IP

Devices & PIC Architecture IP

Fabrication & Processing

High Speed Package & Assembly Design IP

3 Prong Strategy

Product Sales

Patent Licensing*

Technology Transfer

Goals

Make polymers ubiquitous (just like OLEDs)

Have device/PIC teams use EO polymers in their device/PIC designs

Supply polymer modulator OSAs for transceivers

Have foundries use EO polymers in PIC PDKs

Polymers in broad market verticals

*1st commercial material supply license agreement 2Q23 → market acceptance

Source: Lightwave Logic (LWLG)



Is microelectronics and photonics two sides of one coin?

LICHTWAVELOCIC

- Much the same not really (maybe silicon)
- Cut from the same cloth (maybe silicon)
- Double-edged sword certainly
- Two peas in a pod certainly
- Adjacent certainly
- Apples and oranges absolutely
- Two of a kind not quite, some similarities
- In the same league perhaps
- On equal footing not yet, maybe never
- Interchangeable not really
- Parallel not really
- Same, but different perhaps
- Indistinguishable not really



...different ways of looking at or dealing with the same situation...





Symbiotic relationship...

 One can't live with out the other, and both need each other



...remora fish living on the shark...

Microelectronics and photonics... ... symbiotic



Takeaways

 Symbiotic relationship needs upgrading for both electronics and photonics; however, G-AI is changing the playing field...the opportunity is huge...

 Industry needs higher performance packaging, modulators, lower power, higher speed, more linear electronics...

• EO polymers continue to show technical progress with polymer reliability and stability...

 EO polymer materials can scale today, and we are positioning to have EO polymer modulators scale using foundries/OSATs...



Investor Relations Contact

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LIGHTWAVELOGIC Faster by Design

Thank you for listening

lightwavelogic.com

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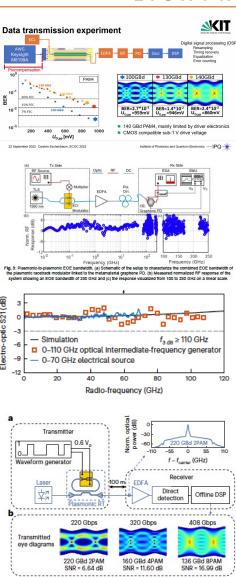






LIGHTWAVELOGIC®

- EO polymer used in different device designs
- Silicon slot, plasmonic slot, plasmonic ring resonator
- All produced world class results*
- Presentations at industry conferences





Competitive polymer positioning



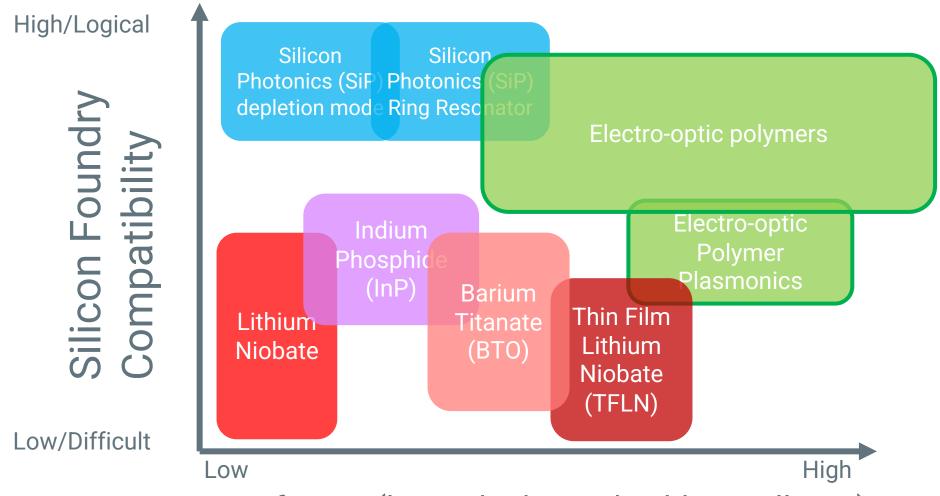
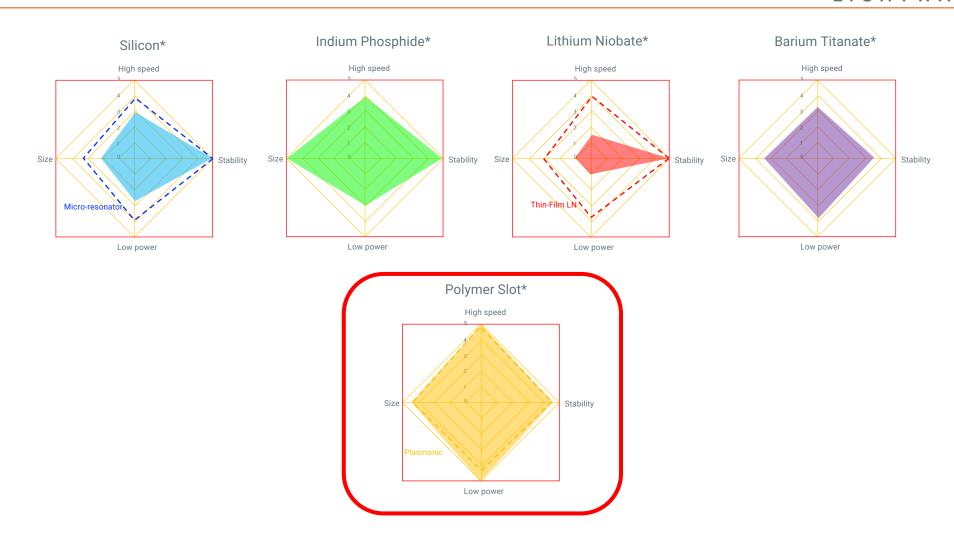


Figure of Merit (low V, high Bandwidth, small size)

Polymer modulators outperform competitive semiconductor technologies

Polymer attributes are impressive...





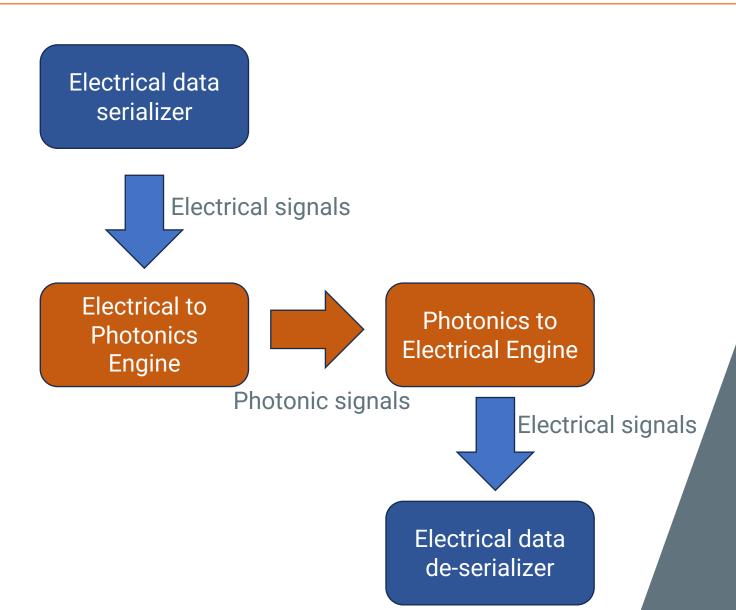
Technology spider chart → **polymers have strong coverage** → **excellent performance**

Source: Lightwave Logic (LWLG), *best estimates 48



Data flow...high level issues





Electrical signals: high loss per distance, but low loss at interfaces

Photonics signals: low loss per distance, but high loss at interfaces

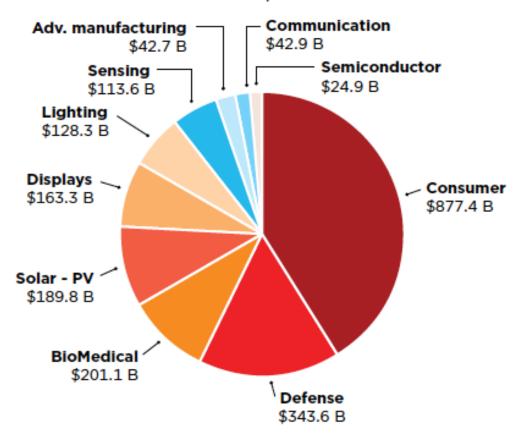






Enabled Markets Economic Impact 2021

Global Total \$2.12 Trillion



Photonics is a large and growing market